PRODUCT / PROCESS CHANGE INFORMATION

| 1. PCI basic data | | |
|----------------------|--|--|
| 1.1 Company | | STMicroelectronics International N.V |
| 1.2 PCI No. | | AMG/18/10705 |
| 1.3 Title of PCI | | Test Flow optimization on A3G4250D and A3G4250DTR. |
| 1.4 Product Category | | A3G4250D and A3G4250DTR (Gyro) |
| 1.5 Issue date | | 2018-02-14 |

| 2. PCI Team | |
|---------------------------|--------------------------|
| 2.1 Contact supplier | |
| 2.1.1 Name | ROBERTSON HEATHER |
| 2.1.2 Phone | +1 8475853058 |
| 2.1.3 Email | heather.robertson@st.com |
| 2.2 Change responsibility | |
| 2.2.1 Product Manager | Andrea Mario ONETTI |
| 2.1.2 Marketing Manager | Marco FERRARESI |
| 2.1.3 Quality Manager | Michele CALDERONI |

| 3. Change | | |
|-----------------|---|----------------------------|
| 3.1 Category | 3.2 Type of change | 3.3 Manufacturing Location |
| Method (EWS-FT) | Different test flow (step removal, step order change, temperature change, quality control steps optimization, test time reduction, etc) if test flow is not defined by Customer. | MALTA |

| 4. Description of change | | |
|---|---|---|
| | Old | New |
| 4.1 Description | Cold test is performed at Final Test in manufacturing flow. | Cold test is removed from Final Test and performed at EWS level on ASIC wafer. Introduction of IR reflow + THS (Temperature Humidity Storage) in the manufacturing flow. |
| 4.2 Anticipated Impact on form,fit, function, quality, reliability or processability? | No Impact. | |

| 5. Reason / motivation for change | |
|-----------------------------------|---|
| 5.1 Motivation | The notified change on Testing Flow for A3G4250D and A3G4250DTR products ensures to optimize the whole manufacturing flow. |
| 5.2 Customer Benefit | SERVICE IMPROVEMENT |

| 6. Marking of parts / traceability of change | | |
|--|--|--|
| | | |
| | | |

| | 7. Timing / schedule |
|-------------------------------------|----------------------|
| 7.1 Date of qualification results | 2018-03-31 |
| 7.2 Intended start of delivery | 2018-05-07 |
| 7.3 Qualification sample available? | Upon Request |

| 8. Qualification / Validation | | | |
|---|-------------|---------------|--|
| 8.1 Description | | | |
| 8.2 Qualification report and qualification results | In progress | Issue Date | |

9. Attachments (additional documentations)

10705 Public product.pdf

| 10. Affected parts | | |
|-------------------------|-------------------------|--------------------------|
| 10. 1 Current | | 10.2 New (if applicable) |
| 10.1.1 Customer Part No | 10.1.2 Supplier Part No | 10.1.2 Supplier Part No |
| | A3G4250DTR | |



Public Products List

Publict Products are off the shelf products. They are not dedicated to specific customers, they are available through ST Sales team, or Distributors, and visible on ST.com

PCI Title : Test Flow optimization on A3G4250D and A3G4250DTR.

PCI Reference : AMG/18/10705

Subject : Public Products List

Dear Customer,

Please find below the Standard Public Products List impacted by the change.

| | A3G4250D | A3G4250DTR | |
|--|----------|------------|--|
|--|----------|------------|--|

IMPORTANT NOTICE - PLEASE READ CAREFULLY

STMicroelectronics NV and its subsidiaries ("ST") reserve the right to make changes, corrections, enhancements, modifications, and improvements to ST products and/or to this document at any time without notice. Purchasers should obtain the latest relevant information on ST products before placing orders. ST products are sold pursuant to ST's terms and conditions of sale in place at the time of order acknowledgement.

Purchasers are solely responsible for the choice, selection, and use of ST products and ST assumes no liability for application assistance or the design of Purchasers' products.

No license, express or implied, to any intellectual property right is granted by ST herein.

Resale of ST products with provisions different from the information set forth herein shall void any warranty granted by ST for such product.

ST and the ST logo are trademarks of ST. All other product or service names are the property of their respective owners.

Information in this document supersedes and replaces information previously supplied in any prior versions of this document.

© 2016 STMicroelectronics - All rights reserved